

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Chee Kiang Yew, et al.**

Art Unit (parent case): **2812**

Serial No.: **TBD**

Examiner (parent case): **Lattin, C.W.**

Filed: **Herewith**

Docket: **TI-26239.1**

For: **Direct Attachment of Semiconductor  
Chip to Organic Substrate**

Conf. No.: **TBD**

**TRANSMITTAL OF FORMAL DRAWINGS**

Commissioner For Patents  
Attn: Official Drafts Person  
Alexandria, VA 22313-1450

**MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)**

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner For Patents, Alexandria, VA 22313-1450.

  
Elizabeth Austin

2/2/2007  
Date

Dear Sir:

Submitted herewith are 2 sheets of formal drawings.

The enclosed drawings are being provided in a timely manner therefore no additional fee is required.

Texas Instruments Incorporated  
P. O. Box 655474, MS 3999  
Dallas, Texas 75265  
(972) 917-5653

Respectfully submitted,



Michael K. Skrehot  
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Reg. No.: 36,682